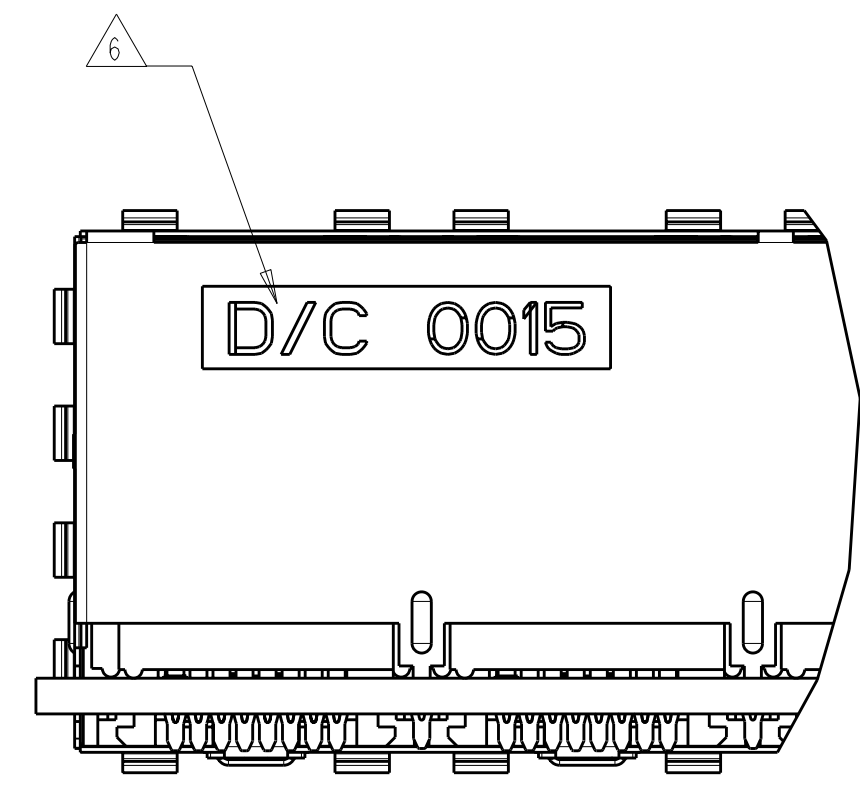
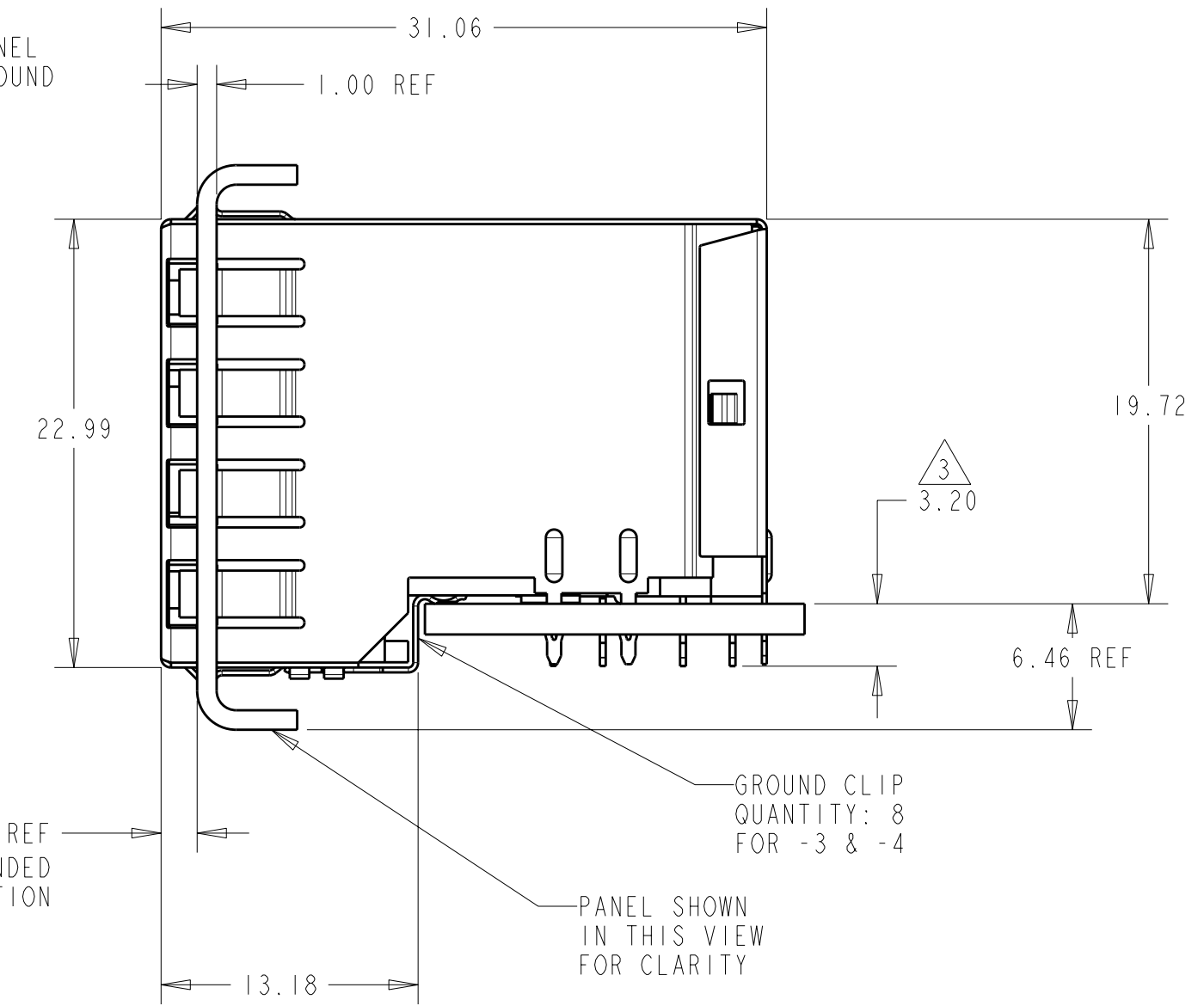
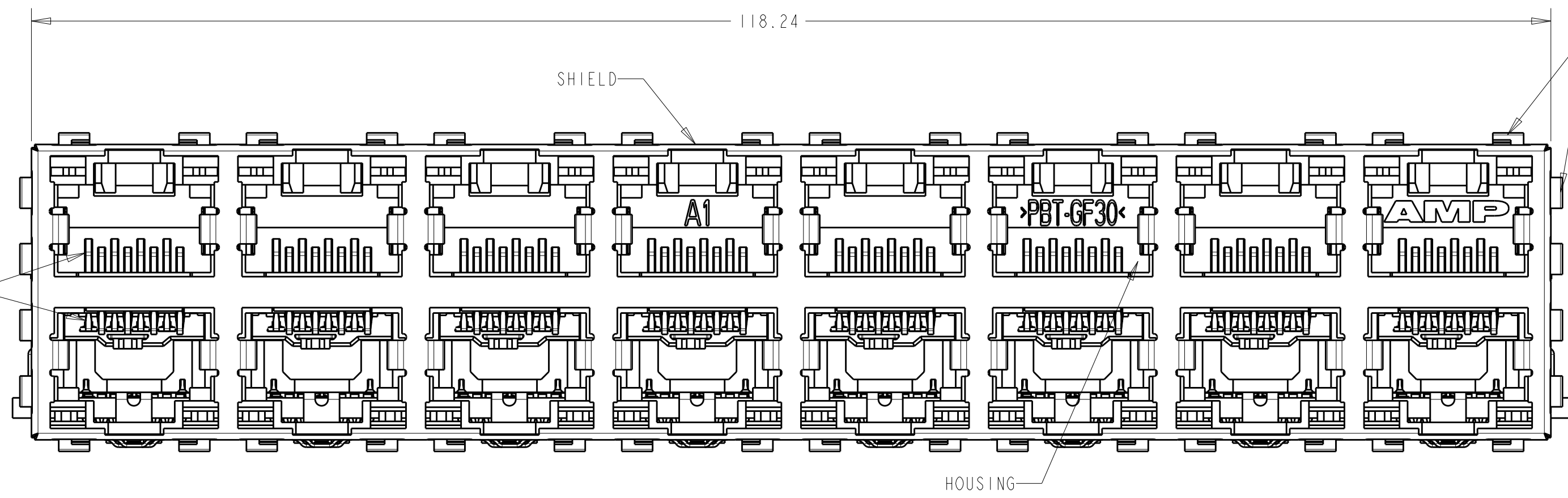
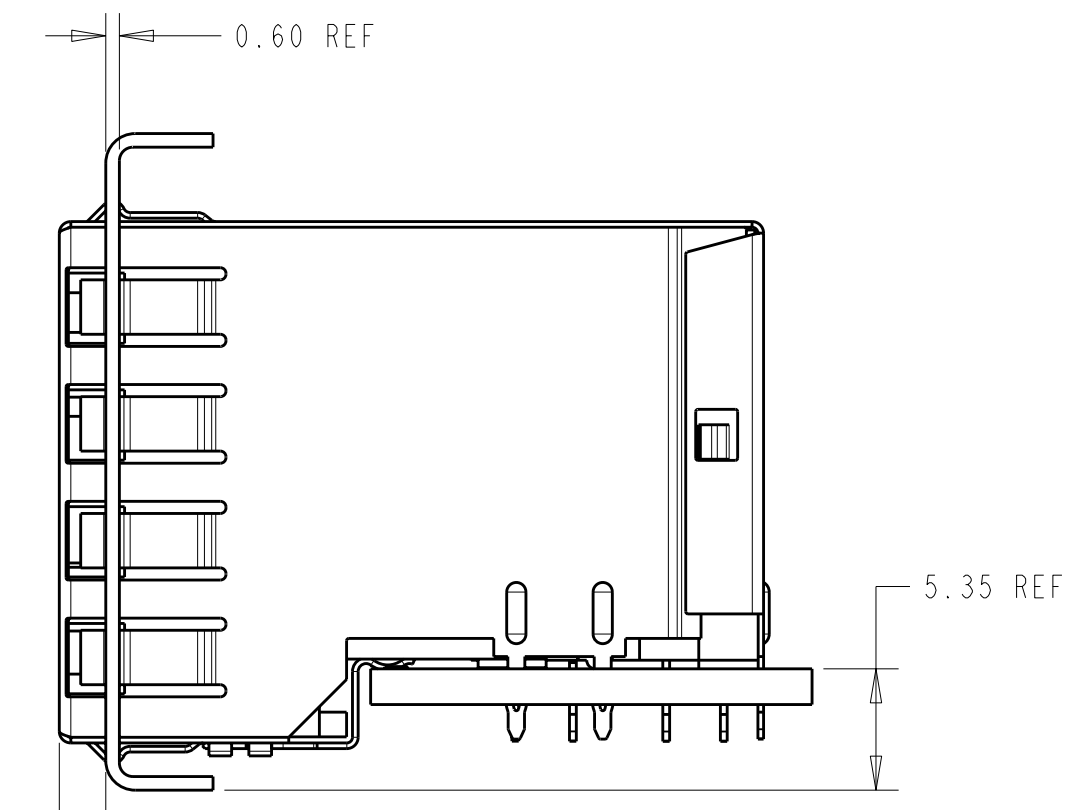


LOC	DIST	REVISIONS			
		REV	DATE	BY	APPD
AA	00	A	RELEASED	28OCT2006	LAM JW
		B	ECO-07-001858	01FEB2007	LAM JW
		C	ECR-08-019486	05AUG2008	A.L S.Y



ATCA PANEL AND PRINTED CIRCUIT BOARD ASSEMBLY LAYOUT

- MATERIAL:
 HOUSING: PBT POLYESTER, BLACK, UL 94V-0
 TERMINALS: 0.33 THICK PHOSPHOR BRONZE PLATED WITH 1.27µm MINIMUM THICK HARD GOLD IN LOCALIZED AREA AND 2.0µm MINIMUM THICK MATTE TIN IN COMPLIANT PIN TERMINAL AREA OVER 1.27µm MINIMUM THICK NICKEL UNDERPLATE
 SHIELD: 0.25 THICK COPPER ALLOY PLATED WITH 2.03µm MINIMUM TIN OVER 1.27 µm MINIMUM NICKEL
 GROUND CLIP: 0.25 THICK COPPER ALLOY PRE-PLATED WITH 2.03µm MINIMUM MATTE TIN OVER 1.27µm MINIMUM NICKEL
 - JACK CAVITY CONFORMS TO FCC RULES AND REGULATIONS, PART 68 SUBPART F.
- ③ MAXIMUM PIN LENGTH 3.40 FROM TOP SURFACE OF PC BOARD
 - ④ FINISHED PLATED THROUGH HOLE DIAMETER - ANNULAR RING DIAMETER 1.3 TO 1.5
 - ⑤ DATUMS AND BASIC DIMENSIONS ESTABLISHED BY CUSTOMER
 - ⑥ DATE CODE LOCATED ON REAR OF PART APPROXIMATELY AS SHOWN
 - ⚠ CONTACTS ARE NOT INTENDED TO BE ALIGNED WITH EACH OTHER

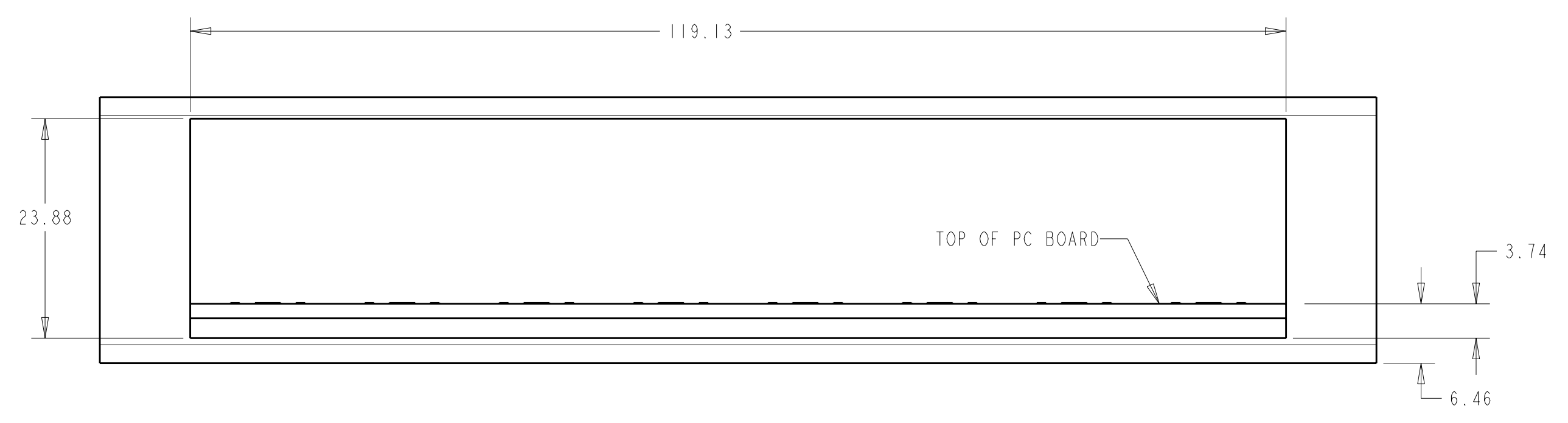


AMC PANEL AND PRINTED CIRCUIT BOARD ASSEMBLY LAYOUT

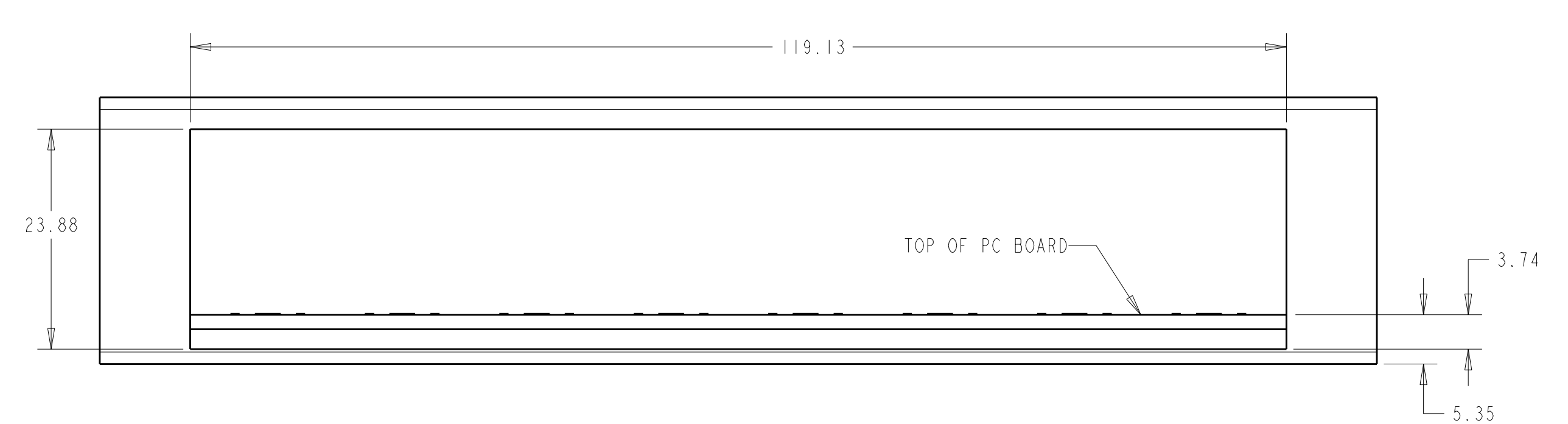
15.88	WITH GROUND CLIP	1888654-4
15.88	WITH GROUND CLIP	1888654-3 (SHOWN)
16.13	WITHOUT GROUND CLIP	1888654-2
16.13	WITHOUT GROUND CLIP	1888654-1
M DIM	DESCRIPTION	PART NUMBER

<small>THIS DRAWING IS UNPUBLISHED. RELEASED FOR PUBLICATION. ALL RIGHTS RESERVED. THIS DRAWING IS CONTROLLED TECHNOLOGY. UNAUTHORIZED DISSEMINATION SHALL BE CONTACTED FOR THE LATEST VERSION.</small>		DWN L.A.MAYER 28OCT2006 CHK J.WESTMAN 28OCT2006 APVD S.FLICKINGER 28OCT2006	Tyco Electronics Corporation Harrisburg, PA 17105-3608
DIMENSIONS: mm 	TOLERANCES UNLESS OTHERWISE SPECIFIED: 9 PLC ± 1 PLC ±0.13 5 PLC ± 4 PLC ± ANGLES ±1°	NAME STACKED MOD JACK ASSEMBLY, 2 X 8, 8 POSN, SHIELDED, PANEL GROUND, OFFSET, CAT 5 PRODUCT SPEC 108-1854 APPLICATION SPEC 114-2160 WEIGHT - FINISH SEE NOTE 1	SIZE CAGE CODE DRAWING NO RESTRICTED TO A1100779 C=1888654 SCALE 1:1 SHEET 1 OF 2 REV C
MATERIAL SEE NOTE 1		CUSTOMER DRAWING	

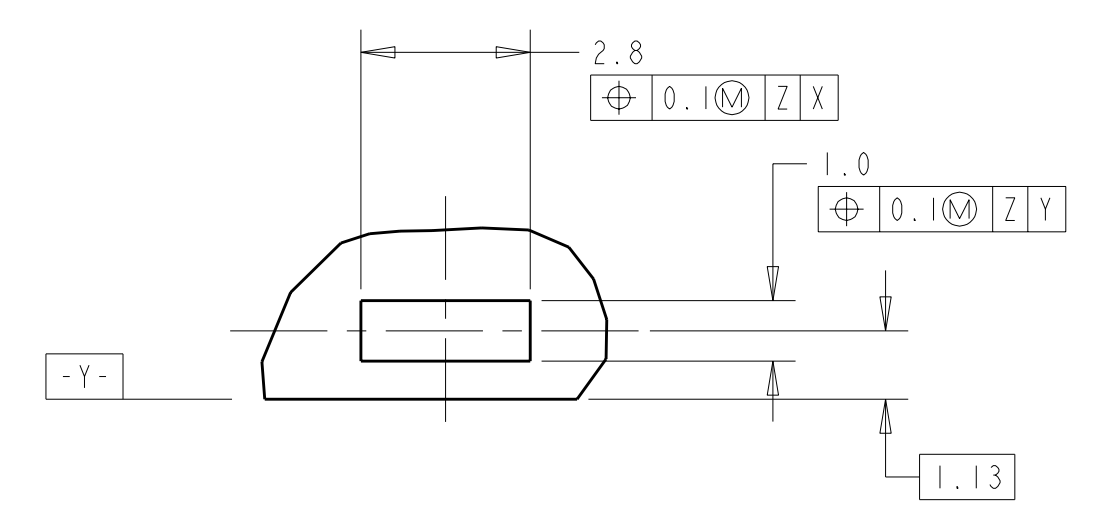
LOC	DIST	REV	DATE	BY	APPD
AA	00				
		1			
		2			



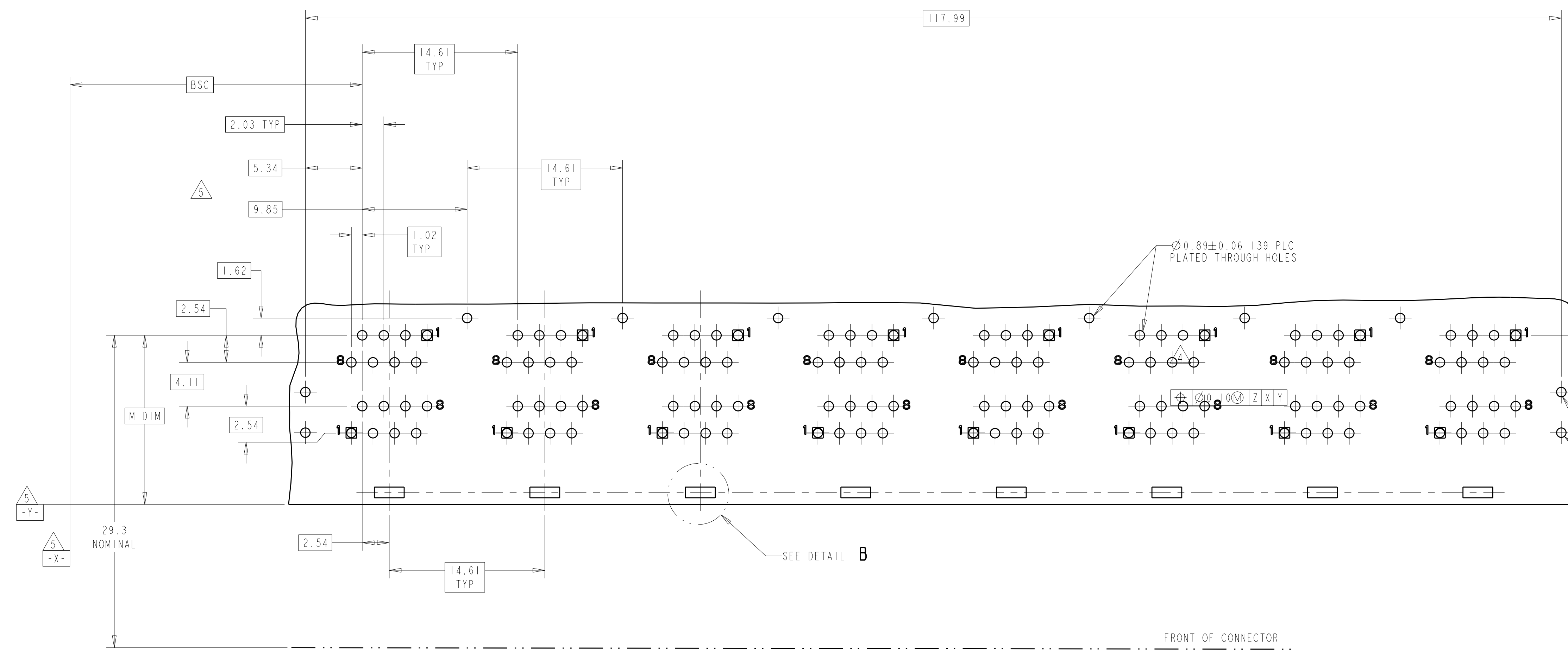
ATCA PANEL AND PRINTED CIRCUIT BOARD LAYOUT
 SCALE 2:1



AMC PANEL AND PRINTED CIRCUIT BOARD LAYOUT
 SCALE 2:1



DETAIL B
 SCALE 8:1
 PLATED PADS REQUIRED FOR 1888654-3 & -4 (PRODUCT WITH GROUNDING CLIP)
 8 PLC



PC BOARD LAYOUT (COMPONENT SIDE)

DIMENSIONS: mm TOLERANCES UNLESS OTHERWISE SPECIFIED: 9 PLC ± 1 PLC ±0.13 5 PLC ± 4 PLC ± ANGLES ±1°		DWN L.A. MAYER 28OCT2006 CHK J. WESTMAN 28OCT2006 APVD S. FLICKINGER 28OCT2006 PRODUCT SPEC 108-1854 APPLICATION SPEC 114-2160 WEIGHT - CUSTOMER DRAWING		Tyco Electronics Corporation Harrisburg, PA 17105-3608 NAME STACKED MOD JACK ASSEMBLY, 2 X 8, 8 POSN, SHIELDED, PANEL GROUND, OFFSET, CAT 5 SIZE CAGE CODE DRAWING NO. RESTRICTED TO A1100779 C=1888654 SCALE 1:1 SHEET 2 OF 2 REV C	
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